



PATENT APPLICATION
Docket No. 9898-206
Client No. SS-15638-US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Shin Kim, et al Conf. No. 6784
Serial No. 10/068,628 Examiner: Dinh, Tuan T.
Filed: February 6, 2002 Art Unit: 2827
For: SEMICONDUCTOR DEVICE BONDING PAD RESISTANT TO
 STRESS AND METHOD OF FABRICATING THE SAME

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

LETTER TO THE OFFICIAL DRAFTSMAN

Pursuant to the Notice of Allowability, mailed June 15, 2004, applicant submits new formal drawings incorporating the required changes.

Customer No. 20575

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.

Hosoon Lee
Limited Recognition Under 37 CFR § 10.9(b)

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450
Date: September 8, 2004

Li Mei Vermilya